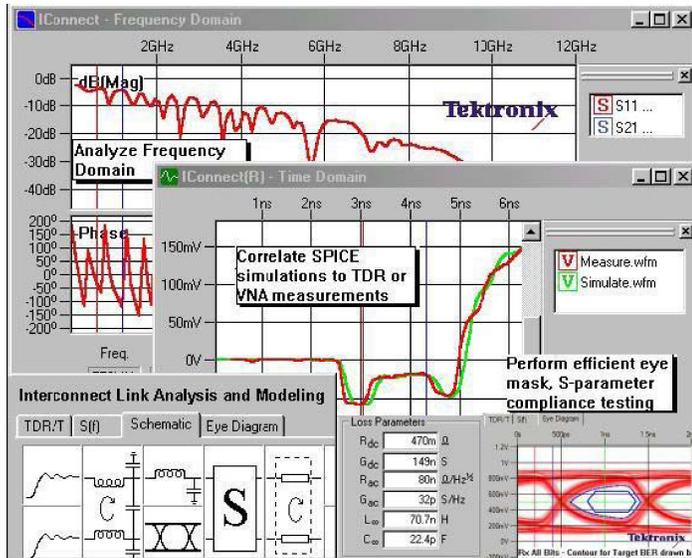


IConnect® SW for DSA8300 Sampling Oscilloscope

80SICMX • 80SICON • 80SSPAR Datasheet



IConnect® software is the efficient, easy to use, and cost-effective solution for measurement-based performance evaluation of gigabit interconnect links and devices, including signal integrity analysis, impedance, Sparameter, and eye-diagram tests and fault isolation. With the help of IConnect and the built-in IConnect Linear Simulator, you can complete interconnect analysis tasks in minutes instead of days, resulting in faster system design time and lower design costs.

Features & benefits

- Quickly Obtain S-parameters using Your TDR Oscilloscope
 - Differential, Single Ended, Mixed Mode; Insertion, Return Loss, Frequency-domain Crosstalk
 - PCI Express, Serial ATA, HDMI, Infiniband, Gigabit Ethernet, Manufacturing, and Standard Compliance Testing including Eye Mask Tests
 - Simplified Calibration Procedure Minimizes Human Errors and Makes Fixture De-embedding a Simple Task
 - Intuitive, Easy, and Accurate for Serial Data, Gigabit Digital Design, and Signal Integrity
- Gain Insight into Interconnect Link Performance through Synthesized Eye Testing
 - Apply Industry Standard (PRBS, CJTPAT, K28.5, HDMI, etc.) or User-specified Stress Patterns
 - Model Effect of Transmitter and Receiver Equalization on Signal Impairment

- Simulate Real-World Signals through Jitter and Noise Insertion
- Measure Computed BER, Eye Opening, Jitter and Noise and do BER Mask Testing at Any Point Along the Data Link
- Easily Analyze Sources of Interconnect Jitter, Losses, Crosstalk, Reflections, and Ringing
 - Analyze Interconnects Concurrently in Time and Frequency Domains
 - Quickly Perform Interconnect Link Analysis and Ensure System-level Simulation Accuracy
 - Obtain More Accurate Impedance and S-parameter Measurements
 - Enhanced TDR Resolution using Industry-best TDR Performance and Z-Line Multi-reflection Impedance Deconvolution Algorithm
 - Fast and Easy Package and PCB Trace Failure Location
 - 50 Ω Calibration Eliminates the Need for Time-consuming Normalization
- Automate your Manufacturing Test and R&D Measurements with Scripts and Programmatic Control
 - Command-line Interface for Many Functions (S-parameters, Z-Line, Others)
- Efficiently Model PCBs, Flexboards, Connectors, Cables, Packages, and Sockets
 - Topological and Behavioral, Measurement Based, Frequency Dependent, Exact SPICE Models
 - Automatically Convert TDR/T or VNA Data into SPICE with MeasureXtractor; Model Passivity, Stability, Causality Guaranteed
- Optimized for use with DSA8300¹ Digital Serial Analyzer Sampling Oscilloscope with 80E10B, 80E08B, and 80E04 True Differential TDR Modules

Applications

- High-speed PCB, Cable Assembly, Connector, and IC Package Testing
- Serial Data Network Analysis
- Compliance Test for SATA, PCI Express, FB-DIMM, HDMI, Fibre Channel, Ethernet, and Other Serial Data Standards
- Consumer Electronics Testing
- Communications Testing
- Computer Testing

¹ Also compatible with DSA8200, TDS/CSA8200, TDS/CSA8000B, and TDS/CSA8000 sampling oscilloscopes.

Software for efficient evaluation of gigabit interconnect links and devices

As clock speeds and rise times of digital circuits increase, interconnect signal integrity dramatically affects digital system performance. Accurate and efficient analysis of the interconnects in time and frequency domains is critical to predict signal losses, jitter, crosstalk, reflections and ringing, digital bit errors, and eye-diagram degradation, and ensure reliable system operation.

The easiest way to perform interconnect S-parameter measurements for serial data network analysis applications

IConnect® S-parameters is the efficient and easy-to-use tool for digital designers, operating at gigabit speeds, to perform single-ended, differential, and mixed-mode S-parameter measurements of interconnects, measure insertion loss, return loss, and frequency-domain crosstalk, and conduct interconnect electrical standard compliance testing.

Efficiency

Operating on the DSA8300 TDR platform, IConnect S-parameters is the most cost-effective and highest throughput approach for S-parameter measurements in digital design, signal integrity analysis, and interconnect compliance testing. It provides as much as a 50% cost savings compared to similar bandwidth VNAs, and dramatically speeds up measurements. You can also take advantage of the IConnect S-parameters command-line interface to add S-parameter measurements to the overall suite of manufacturing tests you perform using your TDR instrument.

Calibration and measurement simplicity

The simplicity of S-parameter calibration using a reference (open, short, or through) and an optional 50 Ω load make the measurement itself, fixture de-embedding, and moving the reference plane a snap. Calibration simplicity minimizes human errors during the measurement. Touchstone file format output enables easy S-parameter file sharing for further data analysis and simulations.

With the addition of the IConnect® S-parameter Wizard, calibration and acquisition of one to four-port single-ended and differential S-parameters is even easier. This “mini-application” guides the user through setup, calibration (including channel deskew) and acquisition of S-parameters and automatically generates Touchstone files for one or multiple DUTs.

Performance

Tektronix offers several true differential TDR modules, which in combination with IConnect allow S-parameters measurements with up to –70 dB of dynamic range. This performance is suitable for serial data analysis, digital design, and signal integrity applications, resolving better than 1% (–40 dB) of crosstalk, and electrical compliance test

masks that typically call for the measurements in the –10 to –30 dB range. The table below summarizes the performance characteristics of these true differential TDR modules. Adding a wider-bandwidth module on the receiver end (e.g., using an 80E09B as a receiver with an 80E10B as a stimulus) will ensure the highest bandwidth for insertion loss measurements.

Table 1: Performance characteristics of true differential TDR modules

Module	Typical Rise Time (10-90%)		S-parameter Bandwidth
	Incident	Reflected	
80E10B	12 ps	15 ps	50 GHz
80E08B	18 ps	20 ps	30 GHz
80E04	23 ps	28 ps	20 GHz

With the long record length acquisitions, IConnect® provides great flexibility for obtaining the desired frequency range and frequency step when performing S-parameter measurements. Up to 1,000,000 points can be acquired.

Efficient and easy interconnect signal integrity analysis and SPICE modeling

IConnect software allows you to quickly and easily generate SPICE and IBIS models for your PCBs, flexboards, connectors, cables, packages, sockets, and I/O buffer inputs directly from TDR/T or VNA S-parameter measurements. IConnect allows you to rapidly analyze eye-diagram degradation, jitter, loss, crosstalk, reflections, and ringing in your digital system. IConnect Linear Simulator allows you to link several interconnect components together to evaluate the total time, frequency-domain performance, and eye diagram of the overall channel.

IConnect® substantially simplifies the signal integrity analysis of the interconnect link, equalization and emphasis component design, and analysis of the interconnect link with transmitter and receiver.

Package, socket, and connector designers

IConnect provides the capability to quickly and easily compute your package, socket, and connector L and C using either the JEDEC or IBIS industry-standard computation procedure, the IConnect MeasureXtractor automatic modeling tool, or additional differential and single-ended TDR modeling procedures. To measure the input or output capacitance of the IC I/O buffer, the same modeling procedures can be applied. These JEDEC L and C measurements can also be automated in manufacturing using the IConnect command line interface.

Cable and connector manufacturers

IConnect® offers the fastest, most cost-effective eye mask, insertion and return loss, and frequency-domain crosstalk specification compliance testing. Impedance, time domain, and S-parameter compliance testing can be performed in manufacturing using the IConnect command-line interface. Eye mask testing allows you to

include the effects of crosstalk on the eye. In addition, IConnect has the capability to easily extract models that include skin effect and dielectric loss, insertion and return loss, eye-diagram degradation, and frequency-dependent RLGC parameters, and analyze the effect of equalization and pre-emphasis on cable assembly performance.

Designers of large computer and server motherboards and communications backplanes

Backplane and motherboard designers can analyze the signal integrity performance of their board, connector, and package interconnects in detail, or predict the eye-diagram degradation in the interconnects due to frequency-dependent transmission line losses and crosstalk using either the built-in links to SPICE simulators, or the IConnect Linear Simulator.

MeasureXtractor™: The fastest way from TDR/T or VNA measurements to simulations

MeasureXtractor is an automated model extraction tool, allowing you to obtain an accurate measurement-based SPICE model of the interconnect, with the press of a button. MeasureXtractor will guide you through the data acquisition process, help you acquire TDR/T or VNA S-parameter data, and will automatically produce an accurate model that matches both the time and frequency response of your interconnect.

Losses, dispersion, jitter, crosstalk, reflections, and ringing are predicted accurately, up to the highest frequency of operation of your instrument. Passivity of models must be explicitly enforced during model extraction, and MeasureXtractor model passivity is assured through proprietary algorithms. This means that interconnect models generated with MeasureXtractor™ will not artificially amplify the signal, oscillate, or produce noncausal results when used in system-level simulations.

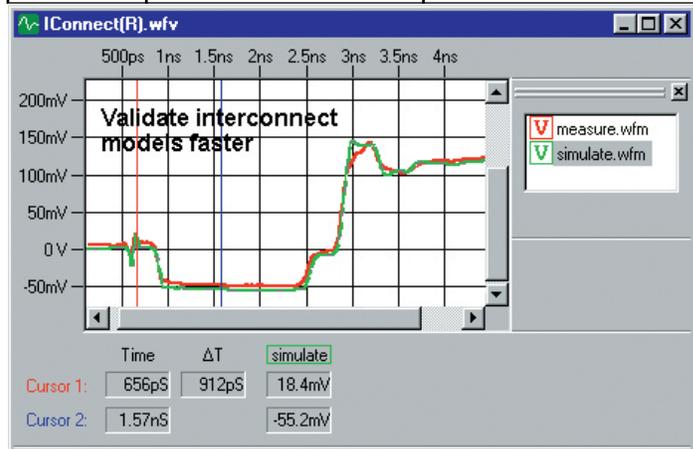
MeasureXtractor produces what is known as a behavioral model. Such a model does not take into account the actual topology of the interconnect, but instead accurately represents the time and frequency behavior of the interconnect in the most simulation-efficient manner; in the case of MeasureXtractor with the minimum number of components and with guaranteed passivity.

Table 2: Comparison of Behavioral and Topological Modeling Approaches

Characteristic	Behavioral	Topological
Measurement Requirements	Requires full-port measurement	Just TDR (reflection) may be sufficient

Table continued...

Characteristic	Behavioral	Topological
Topology Selection	Automatic, no user intervention	User-controlled (easy and intuitive from TDR measurements)
Model Extraction	Automatic, no user intervention	User-driven; more labor intensive and requires more skill
Type of Models	"Black-box", no internal changes allowed	Intuitive, topology correlates to model
Limitations	Large model size for long interconnects (backplanes, cable assemblies)	Efficient model extraction processes exist for large lossy interconnects
Application	Quick inclusion of S-parameter or TDR/T measurements into simulation; the "do-it-all" modeling tool	Comprehensive modeling, "what-if" scenarios analysis, signal integrity troubleshooting, and fault finding

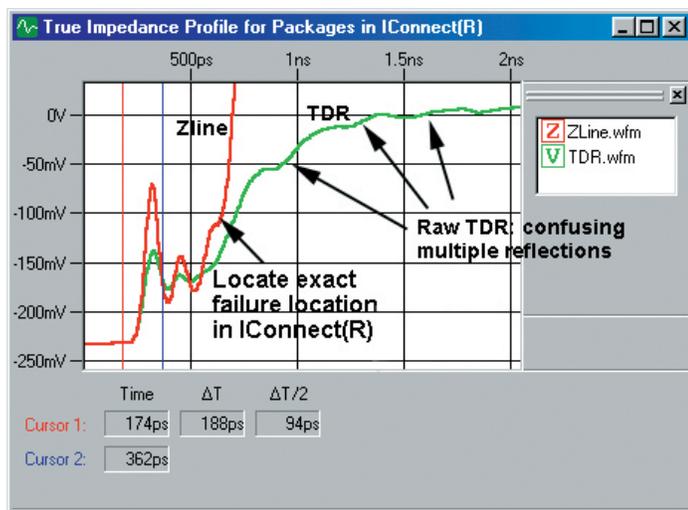


Efficient and easy signal integrity modeling and design validation

IConnect® TDR and S-parameter software provides you with an integrated simulate-and-compare link between SPICE simulators, and TDR or S-parameter measurements, allowing you to quickly validate models produced by IConnect or by outside tools, such as field solvers. You can validate your own models for your board-trace, package, or connector, or the models provided by your vendor. The whole design can be validated using an external SPICE simulator or IConnect Linear Simulator, ensuring that your design works reliably and the eye diagram is within specifications.

The accurate way to measure impedance

IConnect® software uses an impedance deconvolution (Z-Line) algorithm, which further enhances the impedance computation feature in the DSA8300. The Z-Line algorithm efficiently takes care of multiple reflections in the TDR impedance measurement and produces the True Impedance Profile. As a result, you can measure PCB trace impedance more accurately and improve correlation of your data between measurements, including the correlation between such measurements performed by your coworkers or customers in another part of the world. The True Impedance Profile produced by IConnect Z-Line allows you to improve not only the TDR oscilloscope impedance measurement accuracy, but also to increase the TDR oscilloscope resolution. The EZ Z-Line user interface, providing single-button Z-Line computation for any number of waveforms, and enabling easy waveform manipulation and analysis, makes TDR data much easier to interpret.



Package and board failure analysis with TDR

TDR is a reliable nondestructive approach for locating the position of failures in BGA and similar packages and printed circuit boards. IConnect software Z-Line algorithm improves the resolution of TDR, facilitating easier location of open and short faults. When IConnect Z-Line algorithm is used with the 80E10B TDR module with 12 ps incident TDR rise time it enables sub-millimeter resolution for package and on-chip failure analysis. IConnect® EZ Z-Line user interface is specifically designed with a failure analyst in mind, providing single-button Z-Line computation for any number of waveforms, and quick and easy comparison between known good device traces and pins and suspect devices. This makes the TDR data much easier to interpret. Finding the location of open faults and signal-to-ground shorts becomes a simple task, and finding location of plane-to-plane shorts, signal-to-signal shorts, resistive shorts, and faults in fan-outs become realistic tasks.

Specifications

Table 3: Feature summary

Feature		80SSPAR	80SICON	80SICMX
Long Records (up to 1,000,000 points)		X	X	X
Z-Line		X	X	X
	L-C Readouts	X	X	X
	50 Ω Calibration (not required)	X	X	X
S-parameters		X	X	X
	True differential	X	X	X
	Flexible calibration: short, open or thru	X	X	X
	50 Ω calibration (not required)	X	X	X
	Amplitude and phase display	X	X	X
	Touchstone (SnP) file export	X	X	X
L and C Computation using JEDEC Method		X	X	X
Command Line Interface to Z-Line, S-parameters, L-C Computation, Step Spectrum, Eye Diagram, Limit Testing, and Compliance Testing		X	X	X
Eye Diagram			X	X
	From TDR/T or S-parameters		X	X
	From SPICE models		X	X
	Eye diagram with crosstalk effects		X	X
	Industry-standard or user-specified data patterns		X	X
	Transmitter and receiver equalization		X	X
	Jitter/Noise insertion		X	X
	BER, jitter, noise measurements		X	X
	BER eye mask testing		X	X
	Automatic mask shift to fit asymmetric eyes		X	X
Eye-diagram Compliance Tests for HDMI, PCIe, and SATA Standards			X	X
	Auto jitter to close transmitter eye		X	X
	Standard specified patterns		X	X
	Standard specific equalization		X	X
Step Spectrum			X	X
Topological Modeling			X	X
Table continued...				

Feature		80SSPAR	80SICON	80SICMX
	Lossy and lossy coupled		X	X
	Z-Line/Lossless, lumped, or distributed		X	X
	Complete topological modeling system		X	X
PSpice, HSpice, and Berkeley SPICE3 Output Formats			X	X
Integrated Link to Simulators			X	X
IConnect Linear Simulator			X	X
Behavioral Modeling (MeasureXtractor)				X
	Fully automatic modeling, no user intervention			X
	Use TDR/T or VNA S-parameter data for modeling			X
	Model concurrently in time and frequency domains			X

Characteristics

Circuit Simulator Interface Integrated link to HSpice, PSpice, and Berkeley SPICE3
IConnect Linear Simulator

Simulators Included Full version of Berkeley SPICE3
IConnect Linear Simulator

Computer requirements

Characteristic	Description
Processor	1 GHz Intel Pentium (or equivalent)
RAM	1 GB (1 GB recommended for large MeasureXtractor™ runs)
Hard Drive	40 MB free space
Operating System	Microsoft Windows XP / Vista / 7
Monitor	1024/768 or higher resolution. (Additional high-resolution monitor recommended when running IConnect® directly on CSA/TDS8000, CSA/TDS8000B, or CSA/DSA/TDS8200 sampling oscilloscopes)
Others	National Instruments GPIB board, version 2.1 (not required for DSA/CSA/TDS8xxx local TekVISA™ interface)

Ordering information

Models

Options	Description
80SSPAR ²	IConnect® S-parameter and Z-Line software.
80SICON ²	IConnect® Signal Integrity TDR and S-parameter Software.
80SICMX ²	IConnect® and MeasureXtractor™ Signal Integrity TDR and S-parameter Software.

Standard options to 80SSPAR 80SICON and 80SICMX

Opt. USB	USB hardware key (dongle)
Opt. PPD	Parallel port hardware key (dongle)

Upgrade options

Upgrade from 80SSPAR to 80SICON

80SSPARUP

Opt. ICONUSB	Add USB hardware key (dongle)
Opt. ICONPPD	Add parallel port hardware key (dongle)

Upgrade from 80SSPAR to 80SICMX

80SICMX

Opt. ICMXUSB	Upgrade with USB hardware key (dongle)
Opt. ICMXPPD	Upgrade with parallel port hardware key (dongle)

80SICONUP

Opt. ICMXUSB	Upgrade with USB hardware key (dongle)
Opt. ICMXPPD	Upgrade with parallel port hardware key (dongle)

Recommended hardware compatibility

- DSA8300, DSA8200, CSA/TDS8200, or CSA/TDS8000, with 80E10, 80E10B, 80E08, 80E08B, or 80E04 TDR sampling modules (local TekVISA interface is supported; install and run directly on the instrument)
- P80318 – 18 GHz Differential TDR Probe. 80A02 module recommended for static protection of each channel of the sampling or TDR module
- P8018 – 20 GHz Single-ended TDR Probe. 80A02 module recommended for static protection of the sampling or TDR module
- 80A02 – EOS/ESD Protection Module (1 channel). P8018 or P80318 TDR probe recommended

Interconnect cables (3rd party)

Tektronix recommends using quality high-performance interconnect cables with these high-bandwidth products in order to minimize measurement degradation and variations. The W.L. Gore & Associates' cable assemblies, accessible at www.gore.com/tektronix, are compatible with the 2.92 mm, 2.4 mm, and 1.85 mm connector interface of the 80Exx modules. Assemblies can be ordered by contacting Gore.

Calibration kits and accessories (3rd party)

To facilitate S-parameter measurements with these electrical modules and IConnect software, we recommend precision calibration kits, adapter kits, connector savers, airlines, torque wrenches, and connector gauges from Maury Microwave. These components, accessible at www.maurymw.com/tektronix.htm, are compatible with the 2.92 mm, 2.4 mm, and 1.85 mm connector interface of the 80Exx modules. Cal kits and other components can be ordered by contacting Maury Microwave.

² Also available as an option on the DSA8300 sampling oscilloscope. See the DSA8300 data sheet for more information.

CE Marking Not Applicable.



Tektronix is registered to ISO 9001 and ISO 14001 by SRI Quality System Registrar.

Product(s) complies with IEEE Standard 488.1-1987, RS-232-C, and with Tektronix Standard Codes and Formats.

Product Area Assessed: The planning, design/development and manufacture of electronic Test and Measurement instruments.

ASEAN / Australasia (65) 6356 3900
Belgium 00800 2255 4835*
Central East Europe and the Baltics +41 52 675 3777
Finland +41 52 675 3777
Hong Kong 400 820 5835
Japan 81 (3) 6714 3086
Middle East, Asia, and North Africa +41 52 675 3777
People's Republic of China 400 820 5835
Republic of Korea +822 6917 5084, 822 6917 5080
Spain 00800 2255 4835*
Taiwan 886 (2) 2656 6688

Austria 00800 2255 4835*
Brazil +55 (11) 3759 7627
Central Europe & Greece +41 52 675 3777
France 00800 2255 4835*
India 000 800 650 1835
Luxembourg +41 52 675 3777
The Netherlands 00800 2255 4835*
Poland +41 52 675 3777
Russia & CIS +7 (495) 6647564
Sweden 00800 2255 4835*
United Kingdom & Ireland 00800 2255 4835*

Balkans, Israel, South Africa and other ISE Countries +41 52 675 3777
Canada 1 800 833 9200
Denmark +45 80 88 1401
Germany 00800 2255 4835*
Italy 00800 2255 4835*
Mexico, Central/South America & Caribbean 52 (55) 56 04 50 90
Norway 800 16098
Portugal 80 08 12370
South Africa +41 52 675 3777
Switzerland 00800 2255 4835*
USA 1 800 833 9200

* European toll-free number. If not accessible, call: +41 52 675 3777

For Further Information. Tektronix maintains a comprehensive, constantly expanding collection of application notes, technical briefs and other resources to help engineers working on the cutting edge of technology. Please visit www.tek.com.

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